



**GP**  
**ELECTRONICS**

**BSS123K**

**100V N-Channel MOSFET**

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}TYP$	$I_D$
100V	3.0Ω@10V	0.17A
	3.2Ω@4.5V	

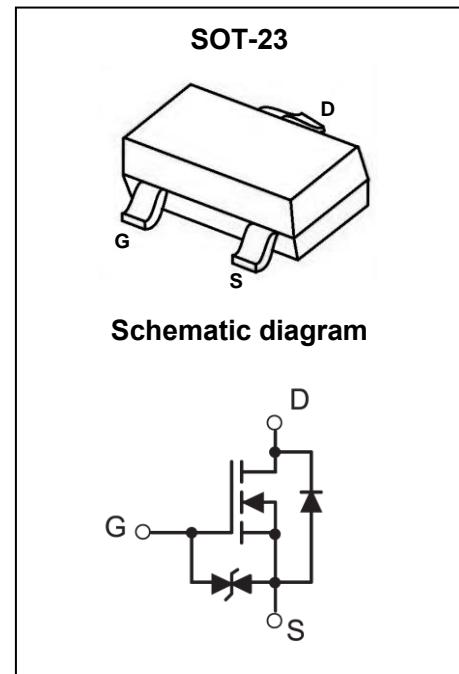
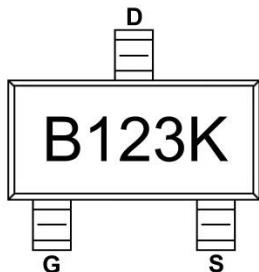
### Feature

- Surface Mount Package
- High Density Cell Design for Extremely Low RDS(ON)
- Voltage Controlled Small Signal Switch
- Rugged and Reliable
- ESD protected Gate

### Application

- Small Servo Motor Controls
- Power MOSFET Gate Drivers
- Switching Application

### MARKING:



### ABSOLUTE MAXIMUM RATINGS (Ta = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current <sup>1,2</sup>	$I_D$	0.17	A
Pulsed Drain Current (tp=10μs)	$I_{DM}$	0.51	A
Power Dissipation	$P_D$	0.35	W
Thermal Resistance from Junction to Ambient <sup>1,2</sup>	$R_{θJA}$	357	°C/W
Junction Temperature	$T_J$	125	°C
Storage Temperature	$T_{STG}$	-55~ +150	°C

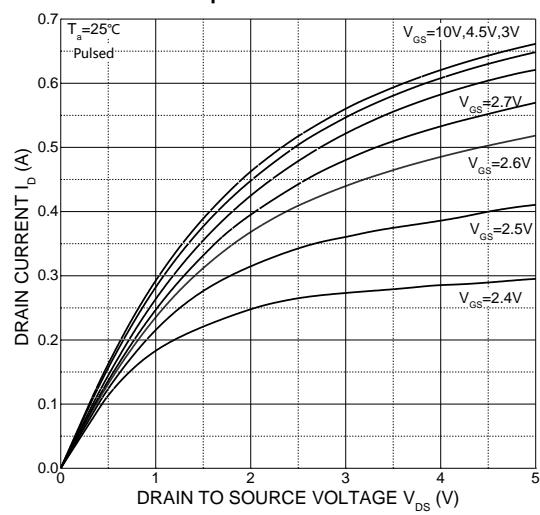
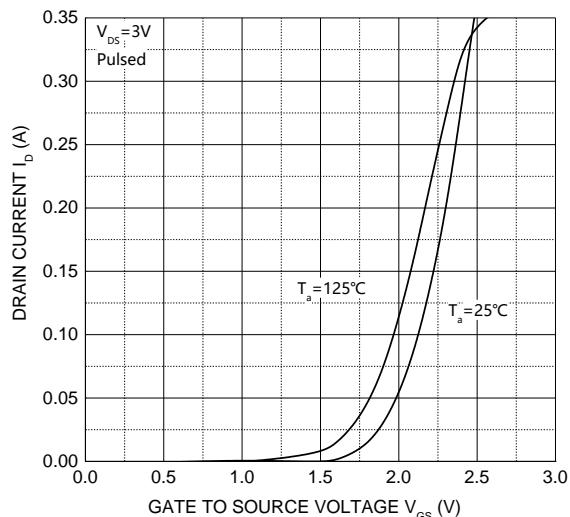
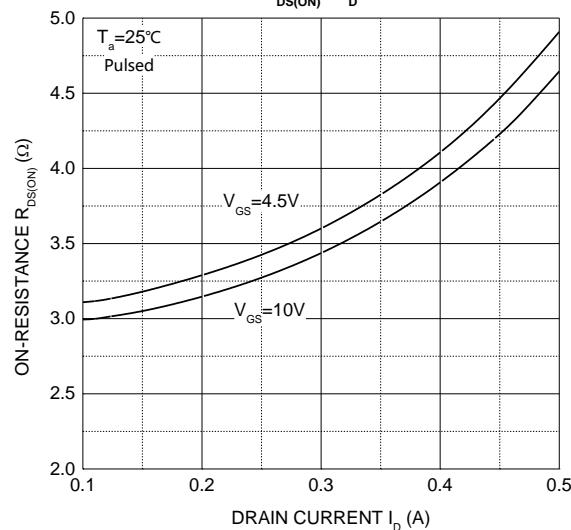
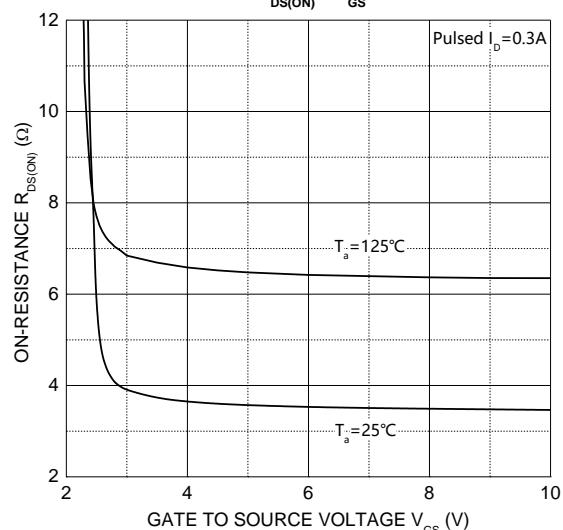
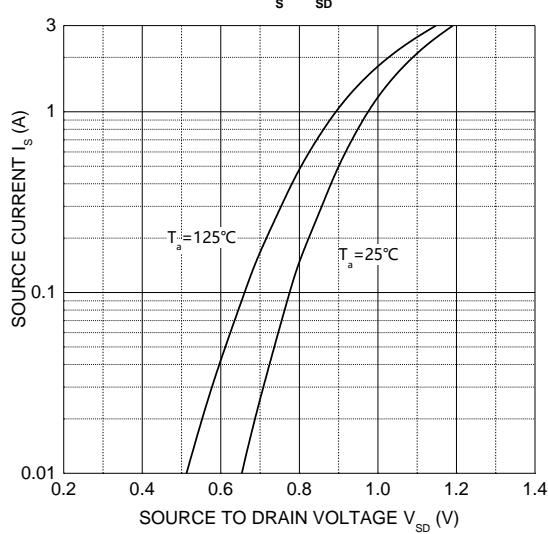
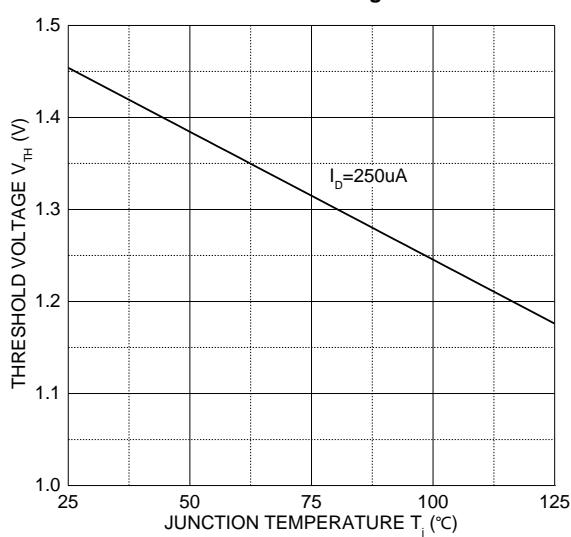
**MOSFET ELECTRICAL CHARACTERISTICS( $T_a = 25^\circ\text{C}$  unless otherwise noted)**

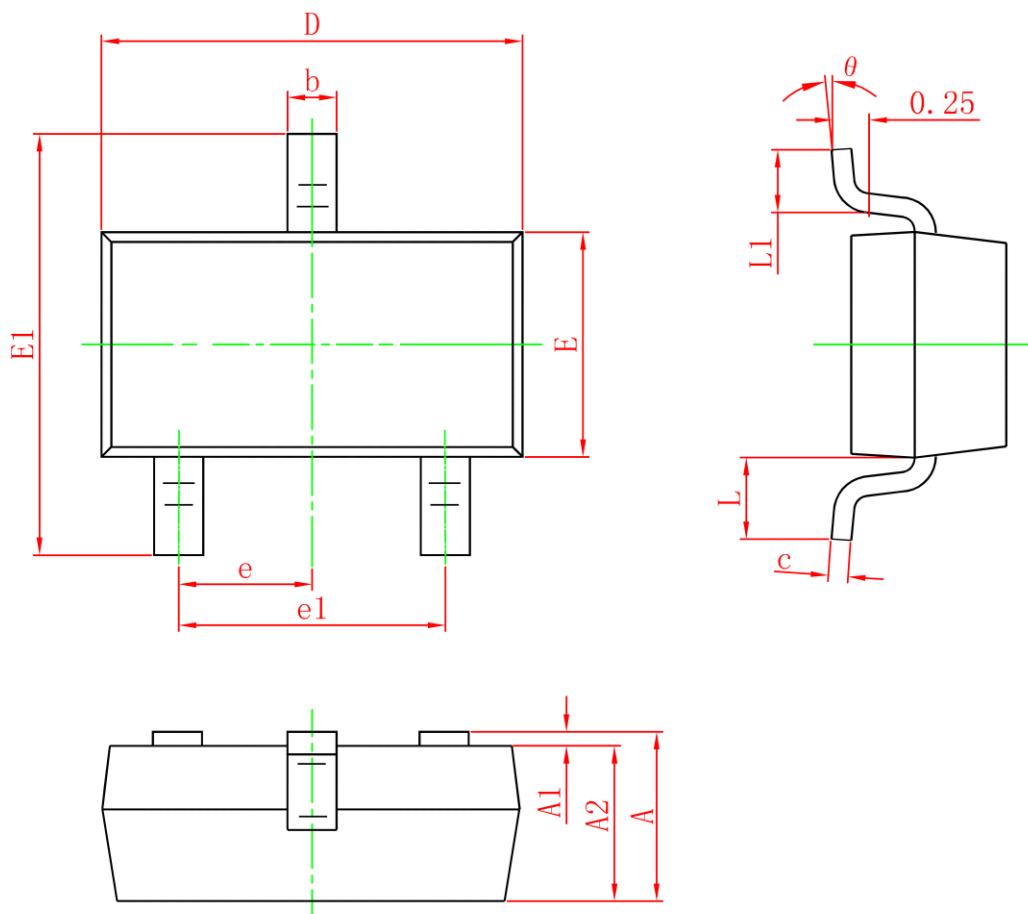
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	100			V
Zero gate voltage drain current	$I_{\text{DSS}}$	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$			1	$\mu\text{A}$
Gate-body leakage current	$I_{\text{GSS}}$	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			$\pm 5$	$\mu\text{A}$
<b>On Characteristics<sup>3</sup></b>						
Gate threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1	1.4	3	V
Drain-source on-resistance	$R_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 0.17\text{A}$		3.0	4.5	$\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 0.17\text{A}$		3.2	6.0	
Forward transconductance	$g_{\text{fs}}$	$V_{DS} = 10\text{V}, I_D = 0.17\text{A}$		0.47		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{DS} = 45\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		29		pF
Output Capacitance	$C_{\text{oss}}$			4		
Reverse Transfer Capacitance	$C_{\text{rss}}$			2		
<b>Switching Characteristics</b>						
Turn-on delay time	$t_{d(\text{on})}$	$V_{GS} = 10\text{V}, V_{DD} = 30\text{V}, I_D = 0.17\text{A}, R_G = 50\Omega$		7		ns
Turn-on rise time	$t_r$			6		
Turn-off delay time	$t_{d(\text{off})}$			10		
Turn-off fall time	$t_f$			9		
Total Gate Charge	$Q_g$	$V_{DS} = 10\text{V}, I_D = 0.17\text{A}, V_{GS} = 10\text{V}$		1.5		nC
Gate-Source Charge	$Q_{gs}$			0.16		
Gate-Drain Charge	$Q_{gd}$			0.2		
<b>Diode Characteristics</b>						
Diode forward voltage <sup>3</sup>	$V_{SD}$	$I_S = 0.17\text{A}, V_{GS} = 0\text{V}$		0.8	1.3	V

Notes :

1.  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR4 board with 1oz. single side copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .
2.  $R_{\theta JA}$  is measured in the steady state
3. Pulse test : Pulse width  $\leq 380\mu\text{s}$ , duty cycle  $\leq 2\%$ .

## Typical Characteristics

**Output Characteristics**

**Transfer Characteristics**

 **$R_{DS(ON)} - I_D$** 

 **$R_{DS(ON)} - V_{GS}$** 

 **$I_s - V_{SD}$** 

**Threshold Voltage**


**SOT-23 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0	0.100	0	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.150	1.500	0.045	0.059
E1	2.250	2.650	0.089	0.104
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°